

Title (en)

METHOD AND APPARATUS FOR CONTROLLING WAFER UNIFORMITY IN A CHEMICAL MECHANICAL POLISHING TOOL USING CARRIER HEAD SIGNATURES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM KONTROLLIEREN DER GLEICHMÄSSIGKEIT VON HALBLEITERSCHEIBEN IN EINEM CHEMISCH-MECHANISCHEN POLIERWERKZEUG UNTER VERWENDUNG VON TRÄGERPLATTENKENNZEICHEN

Title (fr)

PROCEDE ET DISPOSITIF PERMETTANT DE COMMANDER L'UNIFORMITE D'UNE PLAQUETTE DANS UN OUTIL DE POLISSAGE MECANIQUE ET CHIMIQUE A L'AIDE DE SIGNATURES DE TETES DE SUPPORT

Publication

EP 1307909 B1 20061213 (EN)

Application

EP 01950837 A 20010703

Priority

- US 0121142 W 20010703
- US 62773700 A 20000728

Abstract (en)

[origin: WO0211198A2] A method for controlling wafer uniformity in a polishing tool (20) includes providing a plurality of carrier heads (40), determining a signature for each of the carrier heads (40), and installing carrier heads (40) with similar signatures in a polishing tool. A processing line includes a polishing tool (20) and a processing tool (120). The polishing tool (20) is adapted to polish wafers. The polishing tool (20) includes a plurality of carrier heads (40), each carrier head (40) having a polishing signature similar to the other carrier heads (40). The processing tool (20) is adapted to process the polished wafers in accordance with a recipe. At least one parameter in the recipe is based on the polishing signatures of the carrier heads (40).

IPC 8 full level

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CPC (source: EP US)

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